承 認 書

SPECIFICATION FOR APPROVAL

CUSTOMER: _____

DESCRIPTION: WIRE WOUND CHIP INDUCTOR

PART NO: KPS0805LD2R2KST

CUSTOMERMODELNO: _____

DRAWING		
MADE	CHECKED	APPROVED
罗海玲	曾凡强	谢海龙
DATE:	2019年11月12日	

CUSTOMER APPROVE

赣州研创光电科技有限公司

CUSTOMER:		REV NO:	A1.0
DESCRIPTION:	WIRE WOUND CHIP INDUCTOR	PAGE NO:	PAGE 1 OF 8
PART NO:	KPS0805LD2R2KST	SN.	191112270
CUSTOMER NO:		DATE:	2019年11月12日

CATALOG

CUSTOMER:		REV NO:	A1.0
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CUSTOMER NO:		DATE:	2019年11月12日

变更履历

日期	版本	修订内容	制定	核准
2019-11-12	A1.0	新版发行	罗海玲	曾凡强

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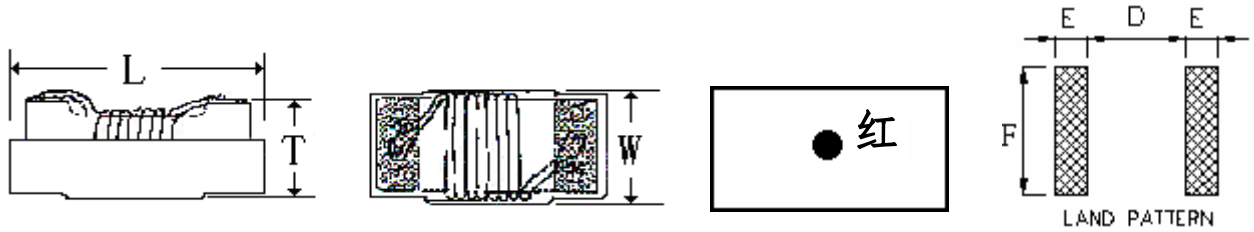
1.SHAPE & DIMENSION

UNIT:mm



CODE	L	W	T	E	F	D	
DIMENSION	2.29MAX	1.73MAX	1.52MAX	1.02Typ.	1.78Typ.	0.76Typ.	

2. ELECTRICAL CHARACTERISTICS @25℃

ITEM	SPEC. RANGE	TEST CONDITION	TEST INSTRUMENTS
L (μH)	2.20±10%	7.9MHz/0.5V	HP4286A
Q(品质系数)	12 Typ	7.9MHz/0.5V	
DCR (Ω)	0.31 MAX		502BC
Irms (mA)	740 MAX		VR116+VR7210
SRF (MHz)	80 MIN		E5071C ENA

3. PART NUMBERING SYSTEM

KPS □□□□ □□ □R□ □ □ □

1 2 3 4 5 6 7

1 PRODUCT SYMBOL（产品代号）
2 DIMENSIONS （规格尺寸）
3 MATERIAL （芯片类型）
4 INDUCTANCE（电感量）
5 TOLERANCE（公差）：J±5%；K±10%；M±20%
6 TERMINAL （端电极材料）： S-锡端头；
7 PACKAGING （包装方式）：T-编带盘装；B –散装

4.GENERAL SPECIFICATION

a. Storage temp.: -40℃ ~ +85℃,R.H.: 30% ~ 70%,Operating temp.: -40℃~ +85℃.

b. Moisture sensitivity level (MSL) 2 (1 year floor life at ＜30℃/85% relative humidity).

c.Failures in time(FIT)/Mean Time Between Failures(MTBF) 38 per billion hours/26,315,789 hours,calculated per Telcordia SR-332.

APPROVED BY	CHECKED BY	DRAFT
罗海玲	曾凡强	谢海龙

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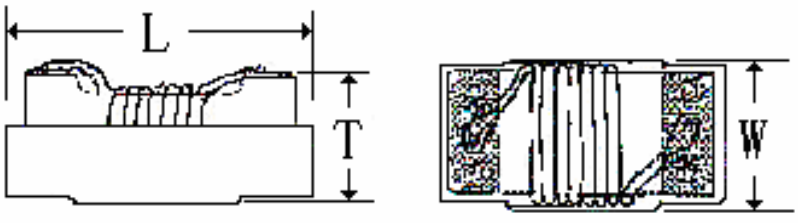
5. TEST DATA FOR SAMPLES

TEST ITEM	L	Q(品质系数)	DCR	L	W	T	
	(μH)	(min)	(Ω)	(mm)	(mm)	(mm)	
CON.	7.9MHz/0.5V	7.9MHz/0.5V	At 25℃	2.29MAX	1.73MAX	1.52MAX	
SPEC.	2.20±10%	12 Typ	0.31 MAX				
1	2.22	17.0	0.27	2.16	1.53	1.25	
2	2.18	17.0	0.27	2.15	1.54	1.22	
3	2.17	18.0	0.26	2.17	1.52	1.23	
4	2.20	18.0	0.25	2.16	1.51	1.25	
5	2.22	16.0	0.27	2.17	1.53	1.24	
6	2.23	16.0	0.25	2.16	1.52	1.24	
7	2.19	16.0	0.25	2.15	1.53	1.25	
8	2.19	18.0	0.25	2.17	1.53	1.26	
9	2.16	16.0	0.25	2.16	1.54	1.25	
10	2.20	16.0	0.26	2.15	1.54	1.26	
X	2.20	16.80	0.26	2.16	1.53	1.25	
R	0.07	2.00	0.02	0.02	0.03	0.04	

图示:



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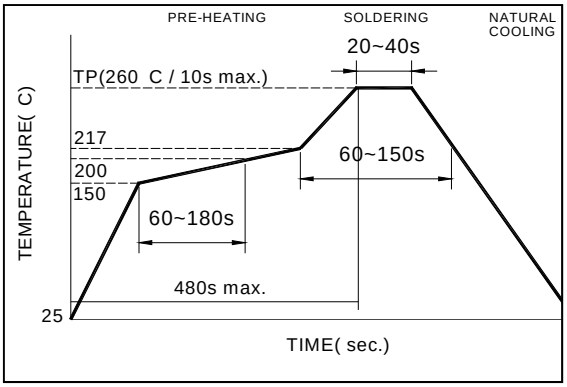
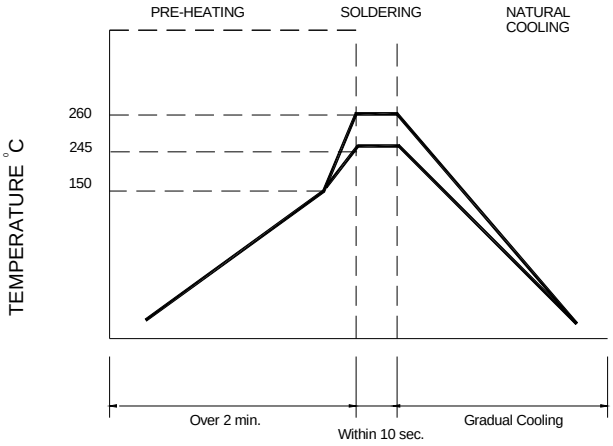
6. SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



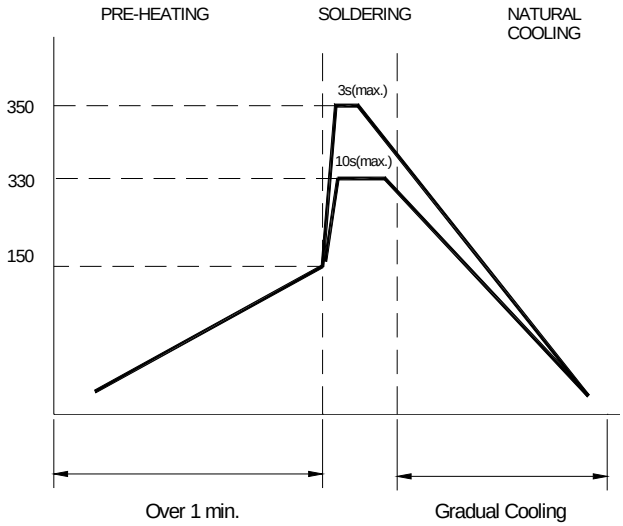
Note：
- Preheat circuit and products to 150℃
- 260℃ tip temperature (max)

Figure 2. Wave Soldering



Note：
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)

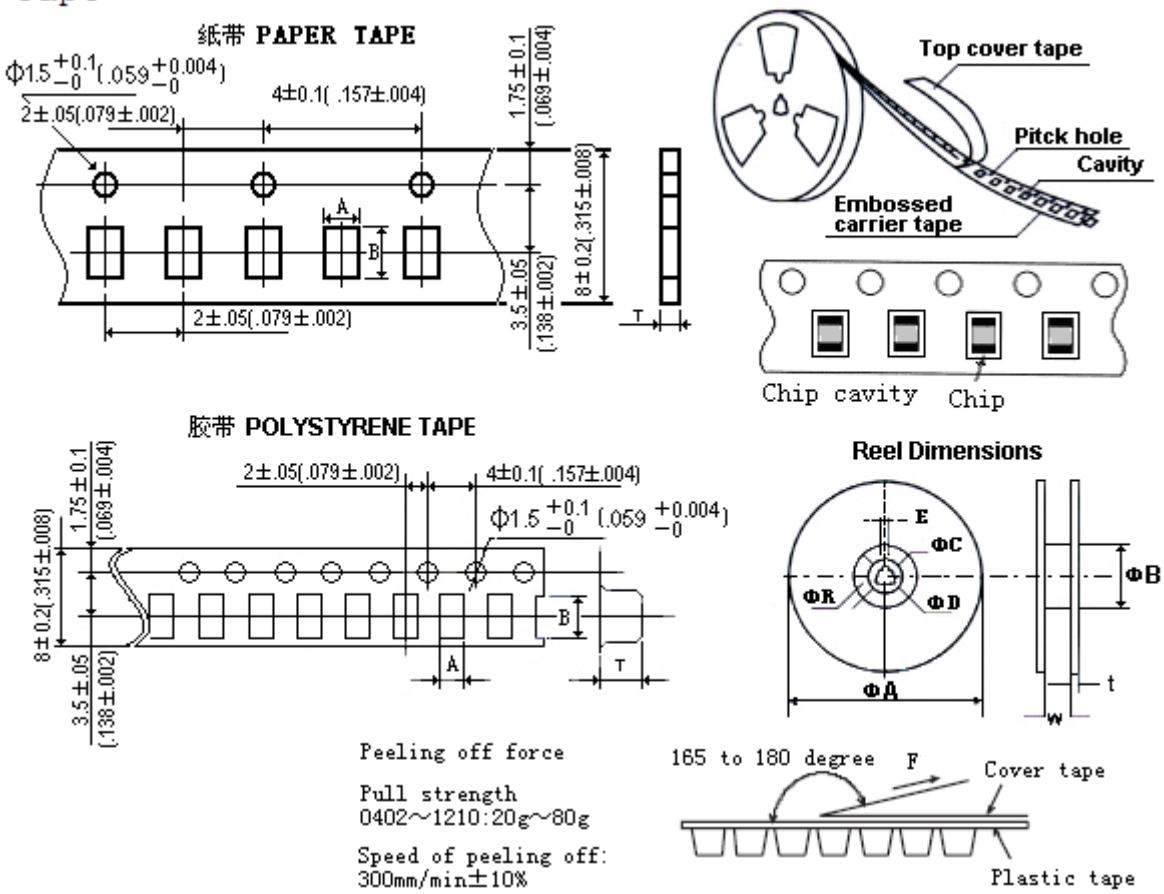
Figure 3. Hand Soldering



Note：
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

7. PACKAGING(unit: mm)

Tape



		A	B	T
纸带	0402	0.74	1.23	0.60
胶带	0603	1.15	1.83	0.95
	0805	1.85	2.40	1.45
	1008	2.73	2.90	2.34
	1210	2.96	3.60	2.40

Type	ΦA	ΦB	ΦC	ΦD	E	W	t	R
0402 ~ 1210	178	60	13	21	2	8.4	2	1

包装数量(PACKAGING QUANTITY)

规格	0402	0603	0805	1008	1210
数量(pcs)	10000	4000	2000	2000	2000

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8. 1 RELIABILITY TEST

TEST ITEM	SPECIFICATION	TEST CONDITION
Rating current	According to product specifications	Current sources:33010D
Inductance	According to product specifications	Test Frequency:0.252~250MHz Test Equipment:HP4291A、HP4286A、HP4287A、HP4284A Test Fixture:16193Aor16334A
Q	According to product specifications	Test Frequency:0.252~1500MHz Test Equipment:HP4291A、HP4286A、HP4287A、Test Fixture:16193Aor16334A
RDC	According to product specifications	Test Equipment:HP4263B
SRF	According to product specifications	Test Equipment:HP4291A Test Fixture:16193A
Solderability	The metalized area must have more then 90%of solder coverage	Soldering Temp:230±5℃ Dipping time:5±1S
Resistance to soldering heat	No evidence of mechanical damage The mealized arer must have more then 75%of solder coverage Inductance change,less than±5% Q change less than±10%	Soldering Temp:260±5℃ Dipping time:10±1S
Thermal Shock	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	A cycle contain:Step1:-40℃，30Min Step 2:85℃，30Min Cycle Times:10

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CUSTOMER:		REV NO:	A1.0
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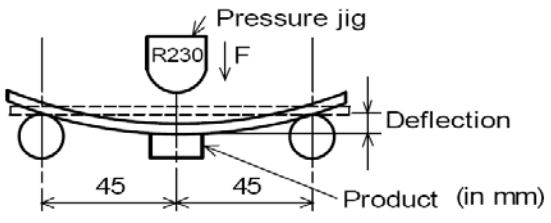
8.2 RELIABILITY TEST

TEST ITEM	SPECIFICATION	TEST CONDITION
High Temperature Storage	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	Test Temperature:125±2℃(Ceramic core)85±2℃(Ferrite core) Test Time:96±2Hours
Low Temperature Storage	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	Test Temperature:-40±2℃ Test Time:96±2Hours
Moisture Resistance	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	Test Temperature:50±2℃ Test Time:100Hours relative humidity:90~95%
Vibration	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	Amplitude:1.5mm X、Y、Z each direction for 1Hour and 45min Frequency range:10~55~10Hz(min)
Component Adhesion	No evidence of mechanical damage No evidence of peel off or broken Keep coutinuity of Winding	Force:2Kg Test Time:5±1sec
Resistance to bend	No evidence of mechanical damage	Camber:20mm Test Board:Glass-Epoxy board Thickness:8mm 
Life	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	Test Temperature:85±2℃ Test Time:1000Hours with rating current

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